

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): An electronic device comprising:

a) an active element, comprising a semiconductor component comprising at least one of a photon or radiation detector, a photon or radiation emission device, ~~a mechanical means,~~
~~an electromechanical means,~~ and a MEMS, said active element having a first and a second face, the first face being provided with electrical connections, arranged on one side only of said active element;

b) a transfer element, comprising a first face and a second face and being assembled to the second face of the active element through its first face, and having electrical connections on its second face, this transfer element being ~~designed~~ configured to be assembled on a surface of another circuit on the side of its second face such that the second face of the transfer element is parallel to the surface of the another circuit; and

c) at least one wire connection between the electrical connections of the first face of the active element and the second face of the transfer element.

Claim 2 (Previously Presented): The electronic device according to claim 1, the transfer element being assembled to the second face of the active element by a layer of glue, a glue film, a glue strip, or soldering means.

Claim 3 (Previously Presented): The electronic device according to claim 1, the wire connection being covered by a protection layer.

Claim 4 (Previously Presented): The electronic device according to claim 1, the transfer element further comprising a ceramic element.

Claim 5 (Canceled).

Claim 6 (Currently Amended): The electronic device according to claim 1, said active element comprising at least one of a CMOS circuit, a CCD circuit, ~~an interconnections network,~~ and a bipolar circuit.

Claim 7 (Canceled).

Claim 8 (Previously Presented): The electronic device according to claim 1, further comprising:

a photon or radiation detector, or a photon or radiation emission device, hybridized onto the first face of said active element.

Claim 9 (Previously Presented): The electronic device according to claim 1, further comprising:

a mechanical or electromechanical device, or a MEMS, hybridized on the first face of said active element.

Claim 10 (Currently Amended): The electronic device according to claim 8 or 9, wherein ~~[[an]]~~ a single element hybridized on the first face of said active element covers all of the electrical connections located on said first face of said active element.

Claim 11 (Previously Presented): The electronic device according to claim 1, the second face of the transfer element further comprising connection balls, pins, or pads.

Claim 12 (Previously Presented): An electronic system comprising:
one or more electronic devices according to claim 11, each transfer element in the one or more electronic devices being connected or fixed to a common substrate through connection balls, pins, or pads.

Claim 13 (Previously Presented): The electronic system according to claim 12, each electronic device being separated from a neighboring electronic device by a distance of less than 60 μm .

Claims 14-16 (Canceled).

Claim 17 (Currently Amended): An electronic device comprising:
a) an active element, comprising a semiconductor component, said active element having a first and a second face, the first face being provided with electrical connections, arranged on only one side of said active element;
b) a transfer element, comprising a first face and a second face and being assembled to the second face of the active element through its first face, and having electrical connections on its second face, the transfer element being ~~designed~~ configured to be assembled on a surface of another circuit on the side of its second face such that the second face of the transfer element is parallel to the surface of the another circuit;

c) at least one of:
a photon or radiation detector,
a photon or radiation emission device,
~~a mechanical or electromechanical device~~, and

a MEMS,
being hybridized onto the first face of said active element; and
d) at least one wire connection between the electrical connections of the first face of the active element and the second face of the transfer element.

Claim 18 (Previously Presented): The electronic device according to claim 17, the transfer element being assembled to the second face of the active element by a layer of glue, a glue film, a glue strip, or soldering means.

Claim 19 (Previously Presented): The electronic device according to claim 17, said wire connection being covered by a protection layer.

Claim 20 (Previously Presented): The electronic device according to claim 17, the transfer element further comprising a ceramic element.

Claim 21 (Currently Amended): The electronic device according to claim 17, said active element comprising at least one of a CMOS circuit, a CCD circuit, ~~an interconnections network,~~ and a bipolar circuit.

Claim 22 (Previously Presented): The electronic device according to claim 17, said active element further comprising at least one of a photon or radiation detector, a photon or radiation emission device, a mechanical means, a electromechanical means, and a MEMS.

Claim 23 (Currently Amended): The electronic device according to claim 17, said at least one of a photon or radiation detector, a photon or radiation emission device, a

~~mechanical or electromechanical device~~, and a MEMS, hybridized on said first face of said active element, covering the electrical connections located on said first face.

Claim 24 (Previously Presented): The electronic device according to claim 17, said second face of the transfer element further comprising connection balls, pins, or pads.

Claim 25 (Previously Presented): An electronic system comprising:
one or more electronic devices according to claim 17, each transfer element in the one or more electronic devices being connected or fixed to a common substrate through connection balls, pins, or pads.

Claim 26 (Previously Presented): The electronic system according to claim 17, each electronic device being separated from a neighboring electronic device by a distance of less than 60 μm .

Claim 27 (Currently Amended): An electronic device comprising:
a) an active element, comprising a semiconductor component, said active element having a first and a second face, the first face being provided with electrical connections, arranged on only one side of said active element;
b) a transfer element, comprising a first face and a second face and being assembled to the second face of the active element through its first face, and having electrical connections on its second face, the transfer element being ~~designed~~ configured to be assembled on a surface of another circuit on the side of its second face such that the second face of the transfer element is parallel to the surface of the another circuit;

c) at least one of:

a photon or radiation detector,

a photon or radiation emission device,

~~a mechanical or electromechanical device,~~ and

a MEMS,

being hybridized onto the first face of said active element and covering at least part of said electrical connections of said first face of said active element; and

d) at least one wire connection between the electrical connections of said first face of said active element and said second face of said transfer element.

Claim 28 (New): The electronic device according to claim 1, wherein the transfer element is configured to connect the active element to the another circuit such that the active element does not have a direct connection to the another circuit.